

In view of the foregoing, Applicant submits that this application is in condition for allowance. Favorable consideration and prompt allowance are earnestly solicited.

Should the Examiner believe that anything further would be desirable in order to place this application in even better condition for allowance, the Examiner is invited to contact Applicant's undersigned representative at the telephone number listed below.

Respectfully submitted,



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<p>DEPOSIT ACCOUNT USE AUTHORIZATION Please grant any extension necessary for entry; Charge any fee due to our Deposit Account No. 15-0461</p>
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APPENDIX

Changes to Claims:

The following is a marked-up version of the amended claim:

2. (Three Times Amended) A semiconductor device having a multiple wiring layer structure, comprising:
- a first conductive layer connected to a conductive member for external connection;
 - a second conductive layer disposed below said first conductive layer, the second conductive layer having a plurality of openings;
 - a third conductive layer disposed below said second conductive layer;
 - a first insulating interlayer disposed between said first conductive layer and said second conductive layer;
 - ~~a- at least one~~ first through hole provided in said first insulating interlayer;
 - a fourth conductive layer filling said at least one first through hole, ~~the fourth conductive layer being a material different from that of the first conductive layer;~~
 - a second insulating interlayer disposed between said second conductive layer and said third conductive layer;
 - ~~a- at least one~~ second through hole provided in said second insulating interlayer the said at least one first through hole disposed substantially directly above said at least one second through hole; and
 - a fifth conductive layer filling said at least one second through hole, ~~the fifth conductive layer being a material different from that of the second conductive layer;~~ wherein said first insulating interlayer and said second insulating interlayer are connected to each other through said openings of said second conductive layer, and a contiguous section of said

first insulating interlayer with said second insulating interlayer is, thereby, formed between said first conductive layer and said third conductive layer.